

Abstract

Microcircuit module intended to be mounted in a microcircuit board

The present invention relates to a microcircuit module (12) intended to be mounted in a microcircuit board, the module including a substrate (16); contact pads (14) supported by the outer face of the substrate, the contact pads being arranged in two series parallel to a first direction (18) of a plurality of contact pads, separated by a central region (20), the contact pads being separated by gaps (22); a microcircuit supported by the inner face of the substrate, and electrically connected to the contact pads via the substrate; and at least one light-emitting component (28) supported by the inner face of the substrate; characterised in that at least one gap portion (30) has a width L larger than the reference width I , this widened portion being positioned outside the theoretical bands (24), the light-emitting component being positioned in the vicinity of the image region of the gap portion, beyond the reference width applied to the gap portion.

Figure 2